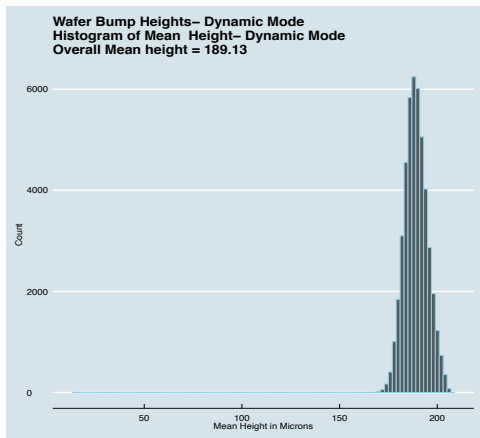


Bumping is a process that can be inspected by MVP's 900 series platforms.

Whether this is on a wafer or another substrate style MVP's Laser Profile technology provides capability processes such as for WLCSP ball place, electroplated C4, and Cu pillar bumping with bump diameters as small as 25 microns.

Our system will inspect multiple materials from copper, to Eutectic Sn/Pb, Pb-free and high-Pb solder alloy.



High Repeatability

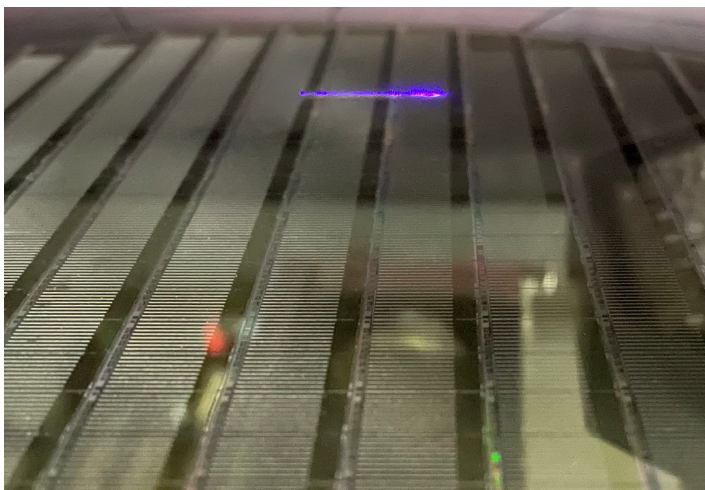
MVP's bump inspection capability is compatible with all our Wafer, Tray, In-Line and Manually loaded systems.

This technology also allows for bump height Metrology on 100mm, 150mm, 200mm and 300mm wafers.

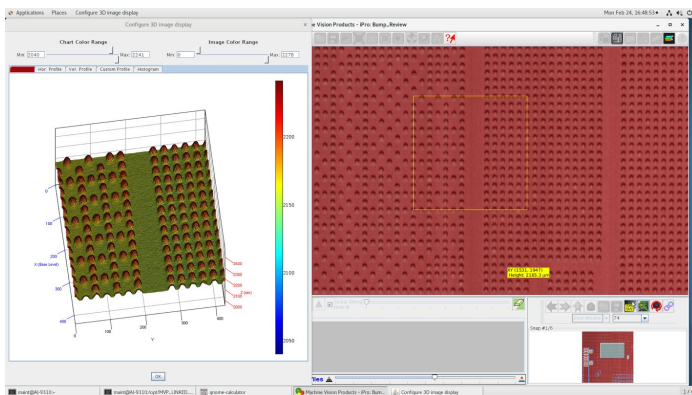
Our ePro guided programming wizard allows programs to be made quickly and accurately. Programs can cover the bump and surface inspection in the same recipe.

MVP's AutoData tools can provide full traceability. Options also allow for Image archiving and full variable data retention.

For more information, please contact MVP.



MVP's 900 Series Laser Profiler



50um Bump